

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Decommission of Newport, Wales wafer fab, as announced on May 5th 2015

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **31-May-2017**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

Decommission of Newport, Wales wafer fab, as announced on May 5th 2015

► **Products affected:**

Sales Name	SP N°	OPN	Package
IRSM836-084MA	SP001546858	IRSM836-084MA	QFN 12X12 36L

► **Detailed Change Information:**

Subject: Transfer of wafer fabrication processing from Newport, Wales to NXP Oak Hill, add ASE Malaysia as new site for PQFN 12x12 Products and change Hana BOM to align with Carsem and ASE BOMs.

Reason: As part of a manufacturing consolidation plan announced in March 2015, Infineon indicated that it would be closing the Fab11 facility and transferring the production capability for certain parts to established SiFo partners, ASE being added to expand capacity and to consolidate assembly BOMs.

Description: Decommission of Newport, Wales wafer fab, as announced on May 5th 2015

Gen 5 HVIC wafer site change , additional assembly site and assembly bill of material change

As the result of this change

	<u>OLD</u>	<u>NEW</u>
Wafer Fab Location	Infineon Technologies Newport Limited	NXP Oak Hill, Austin Texas, US
Assembly and Test Location	Hana Thailand and Carsem Malaysia	Hana Thailand, Carsem and ASE Malaysia
Assembly Bill of Material Change	IC Wire – 1.3 mil Au Leadfinish – Matte Tin	IC Wire – 1.3 mil Cu Leadfinish – NiPdAu

► **Product Identification:** Wafer fab origins will not be distinguished through the external part marking or shipping labels, however, based on the assembly lot code and marked on the device. IFX internal systems will be able to trace the site of the wafer lots used to produce the final product.

► **Impact of Change:** No impact is expected. The new supply chain will meet the same parametric and Qualification level as the existing products. Product Datasheets will remain unchanged.

► **Attachments:**

► **Time Schedule:**

- Final qualification report:
- First samples available:
- Intended start of delivery:

4/07/2017

On request

12-June-2017

If you have any questions, please do not hesitate to contact your local Sales office.